

REMARKS

Claims 1-8 are pending.

In the Office action, the claims were rejected as follows:

(1) Claims 1-4 and 6 were rejected as anticipated by U.S. Patent Publication No. 2002/0028048 (Dair et al.).

(2) Claims 1, 5 and 8 were rejected as anticipated by U.S. Patent Publication No. 2001/0024551 (Yonemura et al.).

(3) Claim 7 was rejected as unpatentable over the Dair et al. publication in view of U.S. Patent No. 6,729,771 (Kim et al.).

As discussed below, applicant respectfully requests reconsideration.

Claim 1 has been amended to clarify that the metal part formed on a side of the dielectric substrate also serves as an outermost surface of the chassis. As explained in the specification, the chassis refers to the outermost member of the framework of the module (page 2, lines 17-19) and the metal part on the side of the dielectric substrate refers to a part where the dielectric and metal plate are fixed together tightly to facilitate heat conduction (page 3, lines 6-8). Thus, according to the claimed subject matter, the metal part on the side of the dielectric substrate is part of the chassis. The claimed subject matter may help improve the thermal properties of the communications module.

The cited references do not disclose or suggest the claimed subject matter. For example, the Dair et al. patent application discloses a fiber optic module that includes a shielding housing or cover 119 that surrounds transmit and receive printed circuit boards (PCBs) 106, 108. Each of the PCBs has a respective ground plane 114, 118 on its inner side. However, those ground planes are separate from the shielding cover 119 and do not serve as an outermost surface of the shielding cover. Therefore, even if the shielding cover were considered to be a chassis and the PCBs 106, 108 were considered to be dielectric substrates, the ground planes 114, 118 do not correspond to the claimed "metal part" on the side of a dielectric substrate.

Similarly, the Yonemura et al. application discloses an optical transceiver 201 (*see e.g.*, FIGS. 12-13) that includes wiring substrates 218, 222 surrounded by a covering member 210, which may be formed of a conductive material (par. [0128]). The outwardly-facing surfaces 218b, 222b of the wiring substrates may be substantially completely covered by a conductive material (par. [0126]). However, in contrast to the claimed subject matter, the outwardly-facing surfaces 218b, 222b are separate from the covering member 210 and do not serve as the outermost surface of the covering member. Therefore, even if the covering member 210 were considered to be a chassis and the substrates 218, 222 are dielectric substrates, the conductive material on the substrates 218, 222 does not correspond to the claimed "metal part" on the side of a dielectric substrate.

At least for the foregoing reasons, claim 1 is not anticipated and should be allowed. Claims 2-6 and 8 are not anticipated and should be allowed for at least the same reasons.

The Kim et al. patent also does not disclose or suggest the features missing from the other references or the subject matter as a whole. Therefore, claim 7 should be allowed as well.

It is believed that all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession of that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reasons for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this paper, and the amendment of any claim does not necessarily signify concession of unpatentability of the claim prior to its amendment.

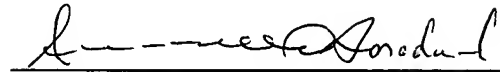
Applicant : Takeshi Fujimoto et al.
Serial No. : 10/628,777
Filed : July 28, 2003
Page : 6 of 6

Attorney's Docket No.: 12852-017001 / 103063-US-00
K. Takahashi

Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

Date: 6/6/05



Samuel Borodach
Reg. No. 38,388

Fish & Richardson P.C.
Citigroup Center
52nd Floor
153 East 53rd Street
New York, New York 10022-4611
Telephone: (212) 765-5070
Facsimile: (212) 258-2291

30235018.doc